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(54) Title: RESIST COMPOSITION

(57) Abstract: There is provided a resist composition used for the production of printed boards, which comprises (A) a resin component, (B) a photopolymerization initiator, (C) water and (D) an organic solvent, wherein the organic solvent (D) contains: (D-1) at least one organic solvent selected from the group consisting of an (-hydroxycarboxylate ester, a (-alkoxycarboxylate ester, a 1,3-diol compound and a 1,3-diol compound derivative, and (D-2) an organic solvent having a hydroxyl group other than (D-1).

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